

IN THE CLAIMS

No claims are amended, added, or cancelled by this response.

INTRODUCTORY COMMENTS

Reconsideration of this application, as amended above, is respectfully requested.

Claims 15-22 have been previously withdrawn from consideration. Claims 1-3, 5-13, 23, and 25-27 are currently pending and stand rejected in the current office action.

REMARKS

Applicants respectfully request consideration of the following remarks.

Rejections Under 35 U.S.C. § 103(a)

In the office action dated October 1, 2004, claims 1-3, 5-13, 23, and 25-27 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Tetsuya (JP-04083363) in view of Yukihiro (JP-0623284). The office action asserts, regarding applicants' independent claims 1 and 13, that Tetsuya shows a package comprising a substrate 2 with an inner surface to which a die 5 is to be attached, forming electrical connections 10 through the substrate, between the die and the exterior of the package; a lid 6 with an inner surface facing the inner surface of the substrate; [t]hermal attach 9 disposed between the die and the inner surface of the lid; [a]nd sealant 7 disposed between the substrate and the lid to bond the lid to the substrate. (Office action dated 10/01/04, page 3, numbered paragraph 4)